Test Beam and Laser Measurements With Irradiated 3D Silicon Strip Detectors

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Test Beam Measurements

Laser Measurements

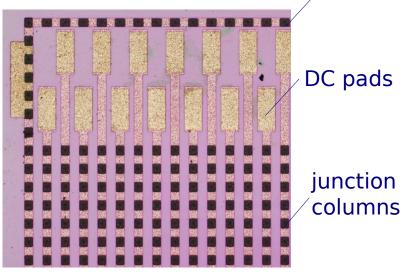
Noise Studies

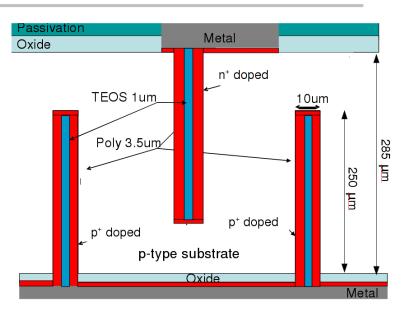


Double-Sided 3D Detectors

- CNM design:
 - 285 µm thick p-type or n-type FZ silicon
 - 250 μ m deep junction columns (n⁺, front side)
 - 250 μm deep Ohmic columns (p⁺, back side) 3D quar







 Detectors irradiated at the proton cyclotron Karlsruhe with 25 MeV protons



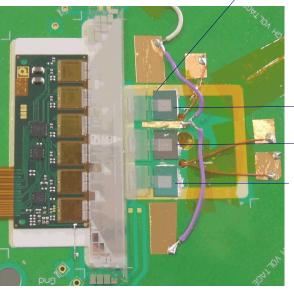
Beam Test Setup

- CERN SPS, H2 beamline (225 GeV pions)
- Tracking provided by Silicon Beam Telescope (SiBT), Resolution ~4 μm

telescope detectors
incident particle
device under test

AC-coupled pitch adapter (HIP, Helsinki)

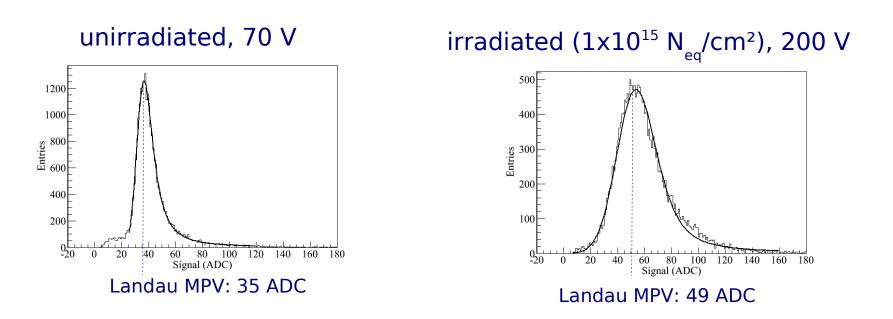
 DAQ: CMS hardware, APV25 front-end (analogue readout)



p-type, unirradiated p-type, $1 \times 10^{15} N_{eq}/cm^2$ p-type, $2 \times 10^{15} N_{eq}/cm^2$



Signal Distribution



 Irradiated detector: higher signal, broader spectrum (also broadened by common mode noise, which could not be completely removed)

 \rightarrow Charge multiplication

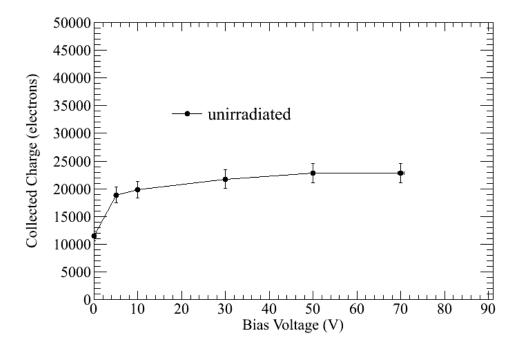
Entries at low signal values: tracks going straight through columns



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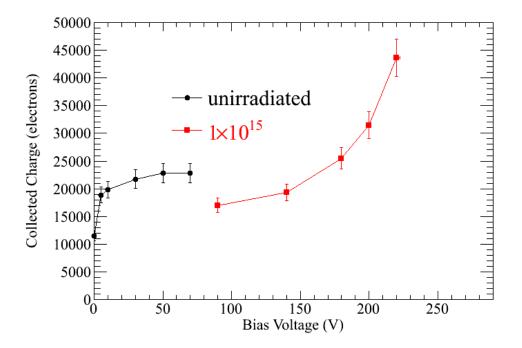
Charge Collection Efficiency

Landau Most Probable Value as a function of bias voltage



Charge Collection Efficiency

Landau Most Probable Value as a function of bias voltage

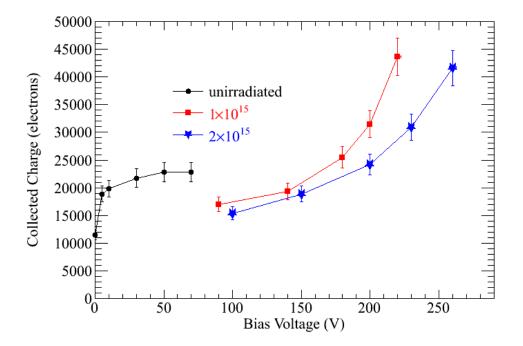


- Irradiated device: increasing signal above ~150 V
 - → Charge Multiplication

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Charge Collection Efficiency

Landau Most Probable Value as a function of bias voltage



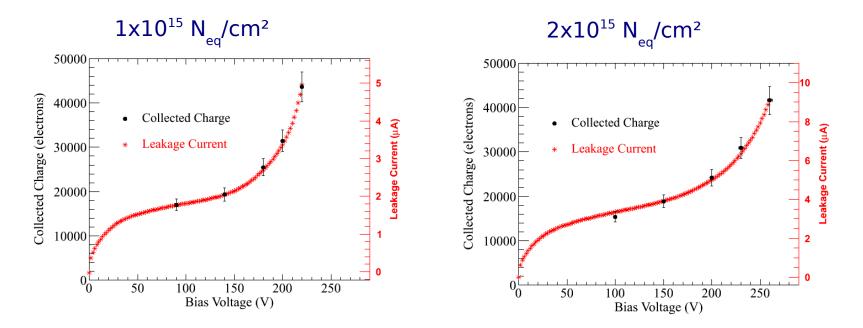
Irradiated devices: increasing signal above ~150 V

→ Charge Multiplication

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Signal and Leakage Current

- Superposition of collected charge and leakage current
 - Leakage current: guard ring current subtracted, measured at ~-20°C

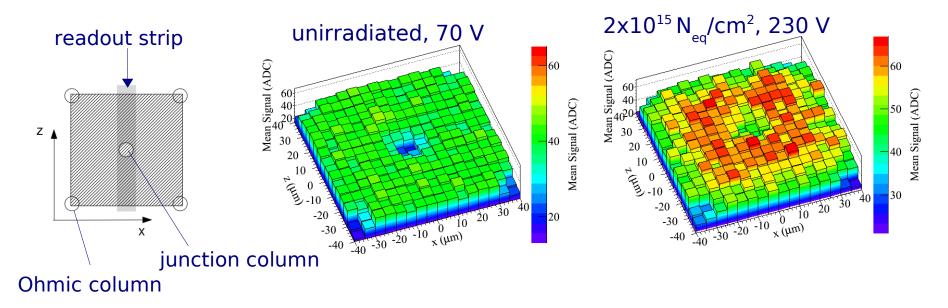


Multiplication also of charge carriers generated thermally



Mean Charge 2D

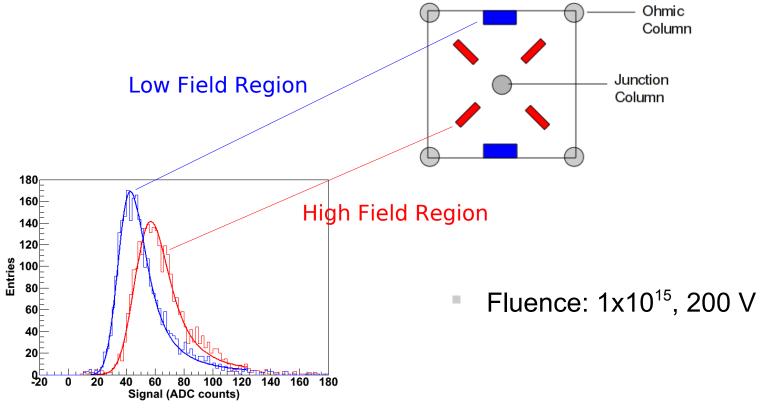
- Mean Signal (not Landau MPV!) superimposed onto unit cell
- Signals of strips around track impact point summed up



- Before irradiation: signal uniform (apart from column positions)
- After irradiation: higher charge multiplication for tracks close to junction column

High Field vs. Low Field

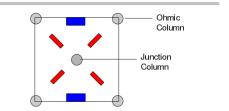
- Signal non-uniformity influenced by electric field variations
 - High field region: along line connecting junction column and Ohmic column
 - Low field region: between columns

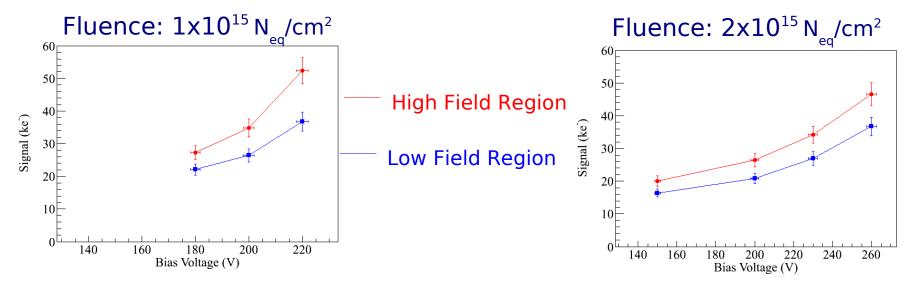


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High Field vs Low Field

Landau MPV versus voltage for tracks in high field region and low field region



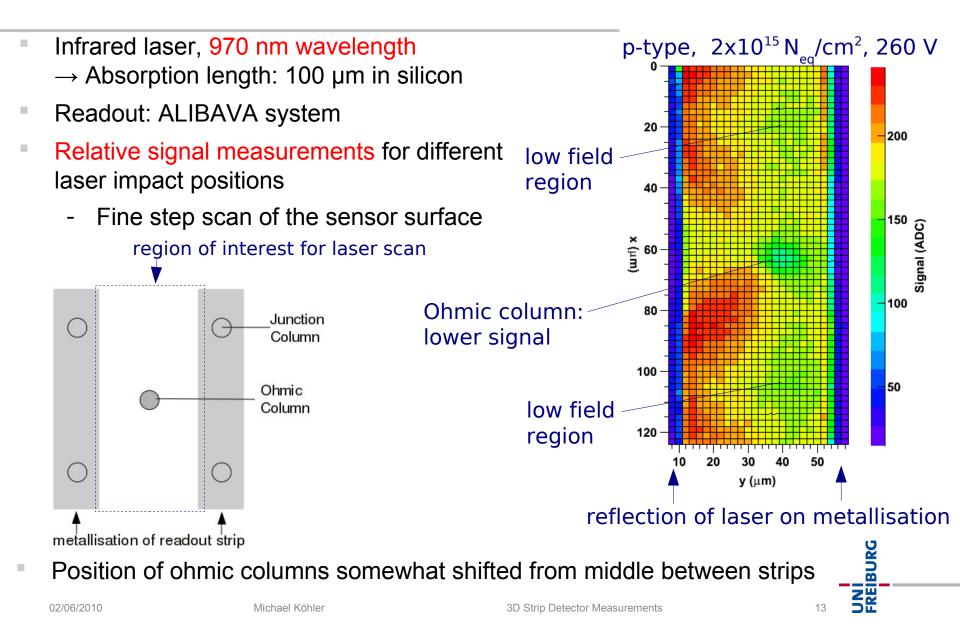


- Multiplication only in thin region around junction column
- Substantially higher signal in region with higher electric field
 - Influenced by different multiplication factors, trapping ...
 - Simulations needed to understand this behaviour quantitatively



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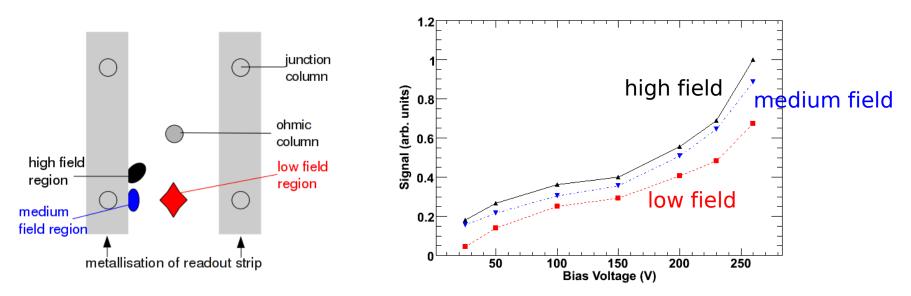
Laser Measurements



Laser: High Field vs. Low Field, p-type

- Investigate signal generated by laser impinging in different regions: high field, medium field, low field
- Here: p-type, 2x10¹⁵ N_{eq}/cm²

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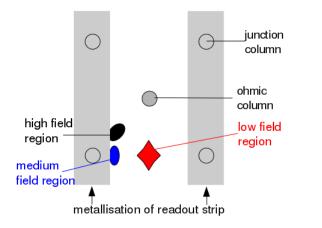


Confirmation of test beam results: ~30% difference between high field and low field regions

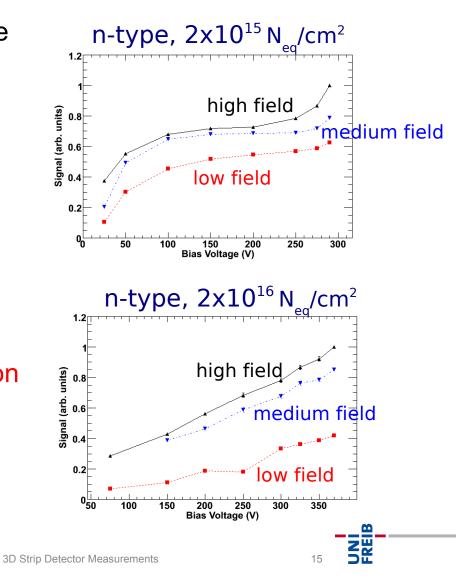
NB: only relative signal measured with laser, not absolute signal!

Laser: High Field vs. Low Field, n-type

 Laser Signal in different regions, n-type detectors

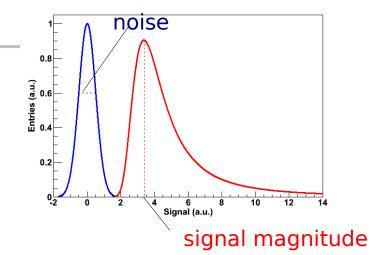


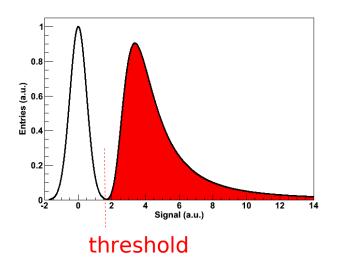
- At 2x10¹⁵ N_{eq}/cm²: Charge Multiplication starting at ~250 V (p-type: 150-200 V)
- Signal non-uniformity increasing with fluence (trapping)



Noise

Ideally: high signal, low noise
 → Signal-to-noise ratio is of importance





In binary systems (as used in ATLAS tracking detectors): signals above a certain threshold are registered

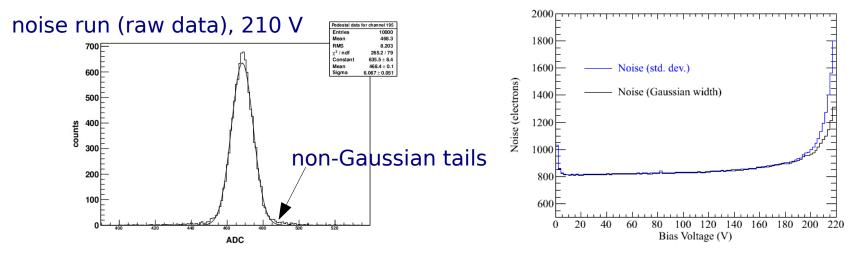
- Threshold must be high enough to suppress noise events: noise occupancy must be limited
- → Signal-to-threshold ratio might be a better criterion

How does charge multiplication influence the noise?



Noise Measurements

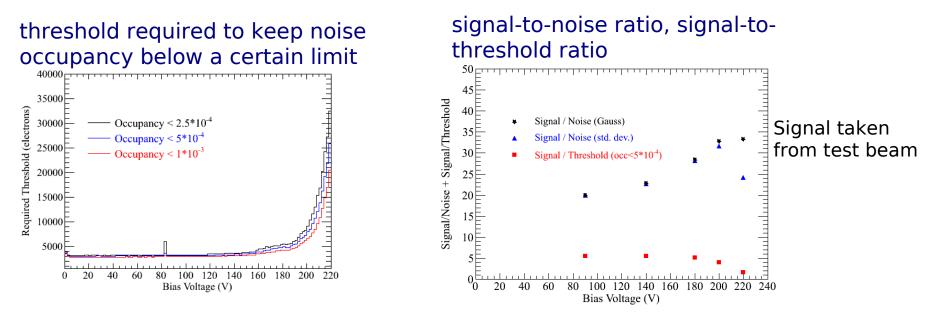
- Noise Measurements:
 - p-type, $1 \times 10^{15} \text{ Neq/cm}^2$ (charge multiplication starting at ~ 150 V)
 - Measured with ALIBAVA readout system



- Charge multiplication: noise is non-Gaussian, pointing to micro-discharge
- Steep noise increase with charge multiplication
- Definition of noise is important at high bias voltages: noise determined from standard deviation is much higher than Gaussian noise

Signal-to-Noise, Signal-to-Threshold $(1x10^{15})$

- p-type, 1x10¹⁵ N_{eq}/cm², T=-20°C
- Threshold (required to keep the noise occupancy below a certain limit) must be increased strongly when charge multiplication is present

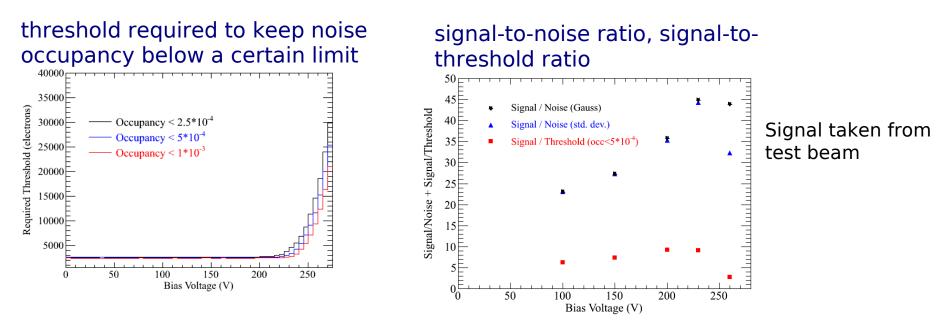


- Here: charge multiplication is
 - Beneficial, if signal / noise is figure of merit
 - Not beneficial, if signal / threshold is figure of merit



Signal-to-Noise, Signal-to-Threshold $(2x10^{15})$

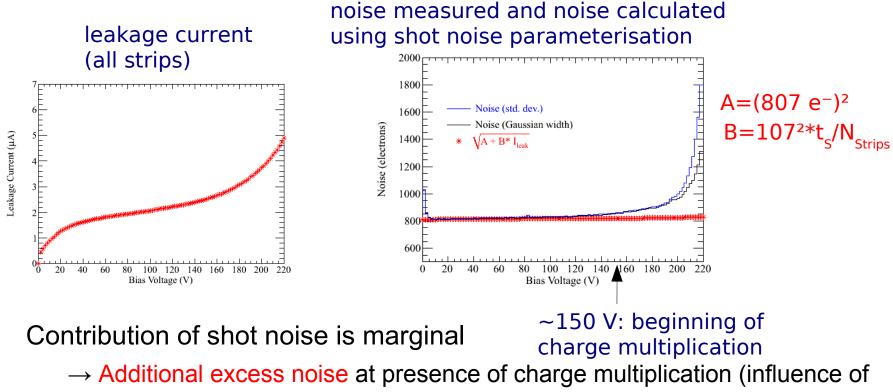
p-type, 2x10¹⁵ Neq/cm², T=-26°C



- Noise increase starting at higher voltages than for detector irradiated to 1x10¹⁵ Neq/cm²
 - Charge multiplication beneficial for Signal / Threshold and Signal / Noise up to certain point
 - Variations from sensor to sensor? Influence from different temperature?

Noise Modelling

- Fluence: 1x10¹⁵ Neq/cm²
- Steep noise increase is not caused by shot noise



varying multiplication)

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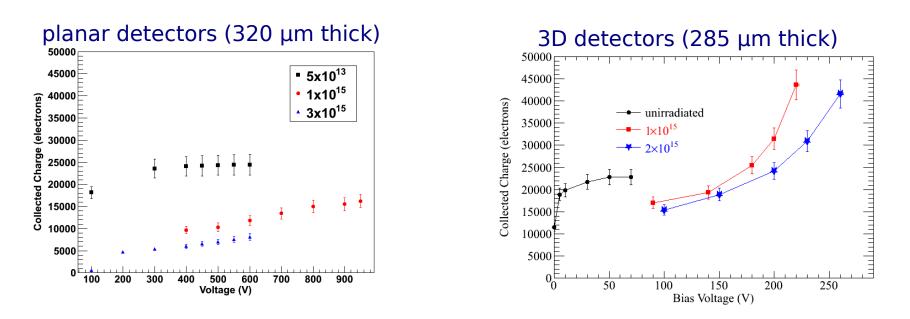
Conclusion

- Charge multiplication measured with double-sided 3D strip detectors
- Space-resolved studies: charge multiplication in thin region around junction column, signal non-uniform
 - Simulations needed to model the behaviour
- Strong noise increase at presence of high charge multiplication
 - Signal-to-noise ratio and signal-to-threshold ratio can be increased, but are decreased at very strong charge multiplication



Planar vs. 3D Detectors

Planar p-type silicon strip detectors were measured in the same test beam



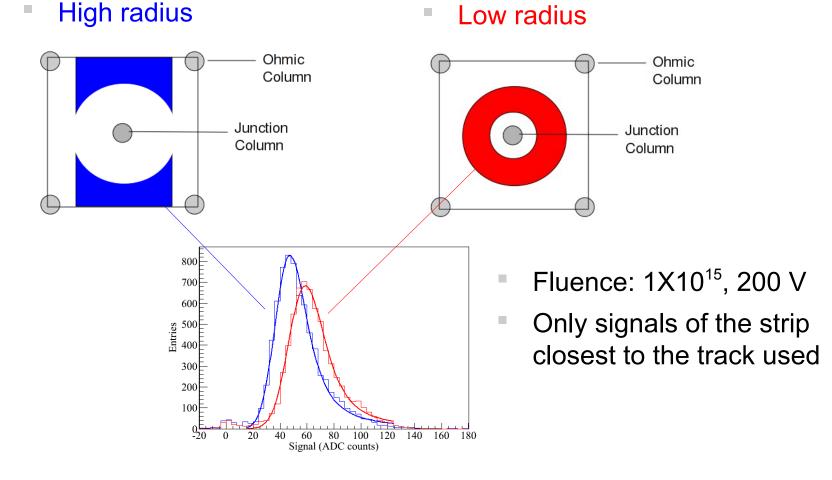
Higher signal measured with irradiated 3D detectors due to early onset of charge multiplication

FREIBURG NB: This only refers to signal, noise must be considered separately!



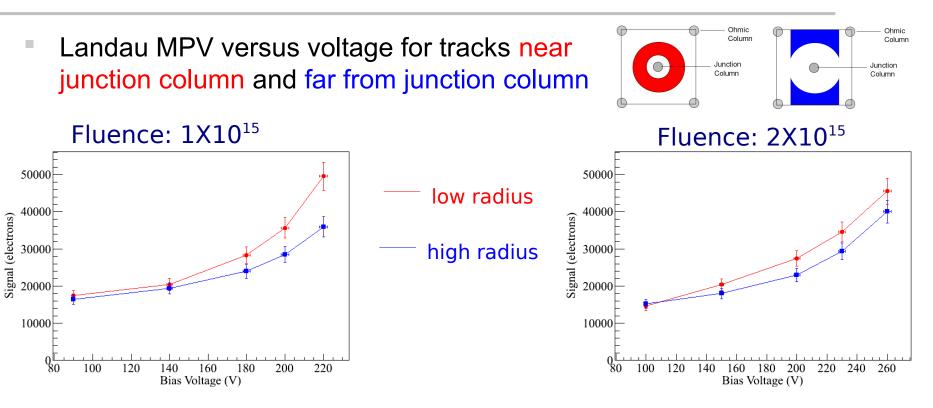
High Radius vs Low Radius

Signal from tracks impinging on different regions within the unit cell:



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High Radius vs Low Radius



- Lower signal from tracks impinging far from junction column
- To what extend caused by trapping? Simulations needed!
- Apparently: charge multiplication, when charge carriers drift through thin region around junction column

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